

L Number	Hits	Search Text	DB	Time stamp
1	17327	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:02
2	150	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 257/777.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:06
3	29	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 257/777.ccls.) and (sink or spreader or (thermal adj (dissipating or dissipation)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 13:40
4	31	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 257/720.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 13:59
5	49	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 257/718.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:01
6	31	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 361/709.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:01
7	27	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 361/709.ccls.) not ((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 257/720.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:01
8	25989	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate or board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:03
9	8662	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate or board))) not ((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:03
10	26	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate or board))) not ((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate))) and 257/777.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:03
11	275	((chip or die) and ((flexible or bend or bending or resilient or wrap or fold or folding) with (interposer or substrate or board))) and 257/686.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 14:06